

WHAT IS CLAIMED IS:

1. A pin header for a transceiver, comprising:
a frame;
a first row of pins extending through the frame at a first angle; and
a second row of pins extending through the frame at a second angle,
wherein the first row of pins is along a first side of the frame and between
indented opposing sides of the frame and the second row of pins is along a
second side of the frame and between the indented opposing sides of the frame.
2. The pin header of claim 1, wherein the first angle is 90 degrees and the
second angle is 90 degrees.
3. The pin header of claim 1, comprising:
a first standoff next to the first row of pins; and
a second standoff next to the second row of pins, wherein the first
standoff and the second standoff are configured to prevent wicking between pins
as the pin header is soldered into place.
4. The pin header of claim 1, comprising:
a first alignment stud in one corner of the frame.
5. The pin header of claim 4, comprising:
a second alignment stud in another corner of the frame.
6. The pin header of claim 1, wherein the pins comprise at least one of brass
and copper.
7. The pin header of claim 1, wherein the pins are at least partially gold
plated.
8. The pin header of claim 1, wherein the pins are round.

9. The pin header of claim 1, wherein the first row of pins comprises five pins and the second row of pins comprises five pins.
10. The pin header of claim 1, wherein each of the pins has a first end and a second end and the first end and the second end are rounded.
11. The pin header of claim 1, wherein the pins are between 0.4 mm to 0.5 mm in diameter and the pins are between 8 mm to 11 mm in length.
12. The pin header of claim 1, wherein a spacing between the first row of pins and the second row of pins is between 9 mm to 11 mm.
13. The pin header of claim 1, wherein a spacing between the pins in the first row of pins and in the second row of pins is between 1mm and 2mm.
14. The pin header of claim 1, wherein the pins are post inserted into the frame.
15. The pin header of claim 1, wherein the pins are overmolded in plastic by the frame.
16. A pin header for a small form factor transceiver comprising:
 - a frame;
 - a first row comprising five pins partially encased in a first portion of the frame; and
 - a second row comprising five pins partially encased in a second portion of the frame, wherein the first portion and the second portion are on opposing sides of the frame and the first portion and the second portion are coupled together by a third portion of the frame.

17. The pin header of claim 16, wherein the frame comprises an hourglass shape.
18. The pin header of claim 17, wherein the first portion is at one end of the hourglass shape and the second portion is at another end of the hourglass shape.
19. The pin header of claim 16, wherein the frame comprises a first standoff adjacent the first row and a second standoff adjacent the second row, the first standoff and the second standoff are configured to maintain spacing between the pins and a printed circuit board.
20. The pin header of claim 16, wherein the frame comprises an alignment stud for aligning the pin header on a printed circuit board.
21. The pin header of claim 16, wherein the third portion of the frame comprises a flat surface configured for picking and placing by automated equipment.
22. The pin header of claim 16, wherein the frame comprises plastic.
23. The pin header of claim 16, wherein the frame is configured to withstand soldering temperatures greater than 220 degrees C.
24. A small form factor transceiver comprising:
 - a housing;
 - a printed circuit board; and
 - a two row by five pin header comprising ten pins soldered to the printed circuit board, wherein the tens pins are aligned to extend through apertures in the housing.

25. The small form factor transceiver of claim 24, wherein the two row by five pin header is configured to allow access to a test point on the printed circuit board between the two rows of pins.
26. The small form factor transceiver of claim 24, wherein the two row by five pin header is configured to allow components to be mounted to the printed circuit board between the two row by five pin header and the printed circuit board.
27. The small form factor transceiver of claim 24, wherein the housing comprises metal.
28. The small form factor transceiver of claim 24, wherein the two row by five pin header is configured to prevent the pins from contacting the housing.
29. The small form factor transceiver of claim 24, wherein the small form factor transceiver is a fiber optic transceiver.
30. The small form factor transceiver of claim 24, wherein the two row by five pin header is configured for soldering to the printed circuit board by automated equipment.
31. A small form factor transceiver comprising:
a housing;
a printed circuit board; and
a two row by seven pin header comprising fourteen pins soldered to the printed circuit board, wherein the fourteen pins are aligned to extend through apertures in the housing.
32. A method for soldering a pin header for a small form factor transceiver to a printed circuit board, comprising:
picking the pin header with an automated pick and place machine;

aligning an alignment stud with a stud hole;
aligning pins of the pin header into solder holes in the printed circuit board; and
soldering the pin header to the printed circuit board.

33. The method of claim 32, wherein picking the pin header comprises picking the pin header on a flat surface of the pin header.

34. The method of claim 32, wherein aligning an alignment stud with a stud hole comprises aligning a pin header alignment stud with a printed circuit board stud hole.

35. The method of claim 32, wherein soldering comprises reflow soldering.

36. The method of claim 32, comprising positioning a standoff from the pin header on the printed circuit board.